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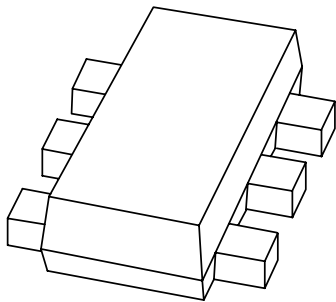
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If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via [salesaddresses@nexperia.com](mailto:salesaddresses@nexperia.com)). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

# DATA SHEET



## **PMEG2005AEV; PMEG3005AEV; PMEG4005AEV**

Very low  $V_F$  MEGA Schottky barrier  
rectifiers

**Very low  $V_F$  MEGA  
Schottky barrier rectifiers**

**PMEG2005AEV; PMEG3005AEV;  
PMEG4005AEV**

**FEATURES**

- Very low forward voltage
- High surge current
- Ultra small plastic SMD package.

**APPLICATIONS**

- Low voltage rectification
- High efficiency DC/DC conversion
- Voltage clamping
- Inverse polarity protection
- Low power consumption applications.

**DESCRIPTION**

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOT666 ultra small SMD plastic package.

**QUICK REFERENCE DATA**

SYMBOL	PARAMETER	MAX.	UNIT
$I_F$	forward current	0.5	A
$V_R$	reverse voltage		
	PMEG2005AEV	20	V
	PMEG3005AEV	30	V
	PMEG4005AEV	40	V

**PINNING**

PIN	DESCRIPTION
1	cathode
2	cathode
3	anode
4	anode
5	cathode
6	cathode

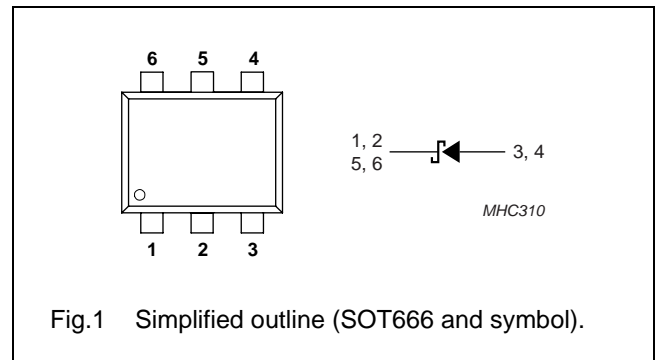


Fig.1 Simplified outline (SOT666 and symbol).

**MARKING**

TYPE NUMBER	MARKING CODE
PMEG2005AEV	G1
PMEG3005AEV	G2
PMEG4005AEV	G3

**RELATED PRODUCTS**

TYPE NUMBER	DESCRIPTION	FEATURE
PMEGxx05AEA	0.5 A; 20/30/40 V very low $V_F$ MEGA Schottky rectifier	SOD323 (SC-76) package
PMEG2005EB	0.5 A; 20 V very low $V_F$ MEGA Schottky rectifier	SOD523 (SC-79) package
PMEG2010EA	1 A; 20 V very low $V_F$ MEGA Schottky rectifier	higher forward current

## Very low $V_F$ MEGA Schottky barrier rectifiers

PMEG2005AEV; PMEG3005AEV;  
PMEG4005AEV

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_R$	continuous reverse voltage				
	PMEG2005AEV		–	20	V
	PMEG3005AEV		–	30	V
	PMEG4005AEV		–	40	V
$I_F$	continuous forward current	note 1	–	0.5	A
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1$ ms; $\delta \leq 0.5$ ; note 2	–	3.5	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8$ ms; square wave; note 2	–	10	A
$T_j$	junction temperature	note 3	–	150	°C
$T_{amb}$	operating ambient temperature	note 3	–65	+150	°C
$T_{stg}$	storage temperature		–65	+150	°C

### Notes

1. Refer to SOT666 standard mounting conditions.
2. Only valid if pins 3 and 4 are connected in parallel.
3. For Schottky barrier diodes thermal runaway has to be considered, as in some applications, the reverse power losses ( $P_R$ ) are a significant part of the total power losses. Nomograms for determination of the reverse power losses  $P_R$  and  $I_{F(AV)}$  rating will be available on request.

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	in free air; notes 1 and 2	405	K/W
		in free air; notes 2 and 3	215	K/W
$R_{th\ j-s}$	thermal resistance from junction to soldering point	note 4	80	K/W

### Notes

1. Refer to SOT666 standard mounting conditions.
2. For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses. Nomograms for determination of the reverse power losses  $P_R$  and  $I_{F(AV)}$  rating will be available on request.
3. Device mounted on an FR4 printed-circuit board with copper clad 10 × 10 mm.
4. Solder point of cathode tab.

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PMEG2005AEV; PMEG3005AEV;  
PMEG4005AEV

### ELECTRICAL CHARACTERISTICS

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	PMEG2005AEV		PMEG3005AEV		PMEG4005AEV		UNIT
			TYP.	MAX.	TYP.	MAX.	TYP.	MAX.	
$V_F$	forward voltage	$I_F = 0.1\text{ mA}$	90	130	90	130	95	130	mV
		$I_F = 1\text{ mA}$	150	190	150	200	155	210	mV
		$I_F = 10\text{ mA}$	210	240	215	250	220	270	mV
		$I_F = 100\text{ mA}$	280	330	285	340	295	350	mV
		$I_F = 500\text{ mA}$	355	390	380	430	420	470	mV
$I_R$	continuous reverse current	$V_R = 10\text{ V}$ ; note 1	15	40	12	30	7	20	$\mu\text{A}$
		$V_R = 20\text{ V}$ ; note 1	40	200	–	–	–	–	$\mu\text{A}$
		$V_R = 30\text{ V}$ ; note 1	–	–	40	150	–	–	$\mu\text{A}$
		$V_R = 40\text{ V}$ ; note 1	–	–	–	–	30	100	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1\text{ V}$ ; $f = 1\text{ MHz}$	66	80	55	70	43	50	pF

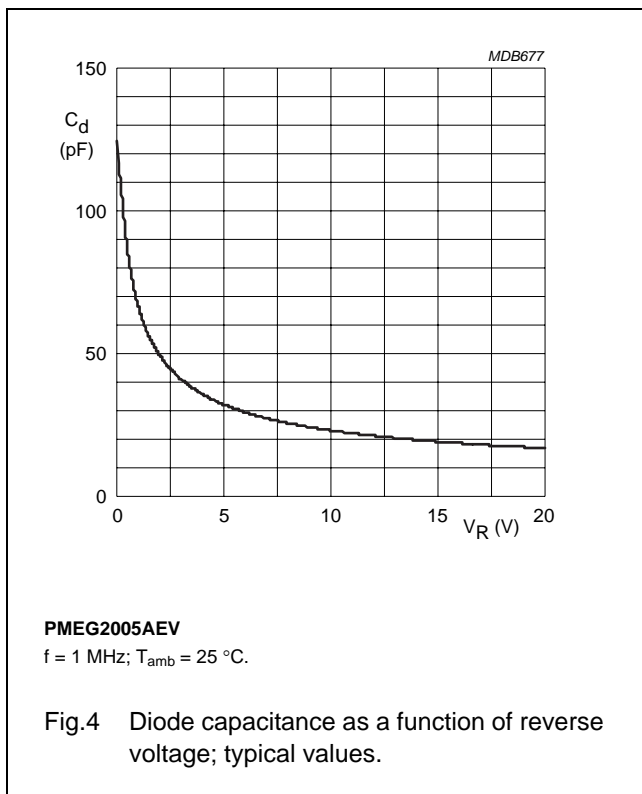
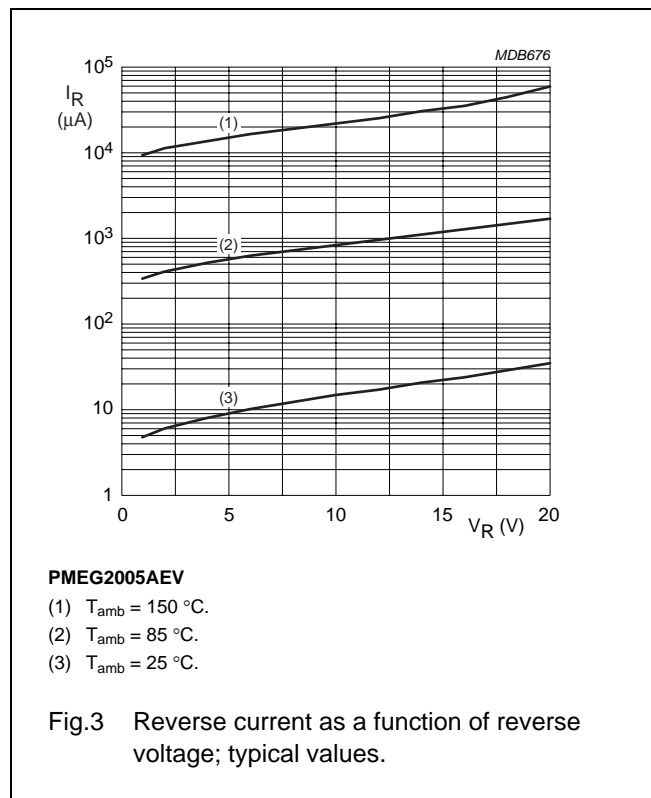
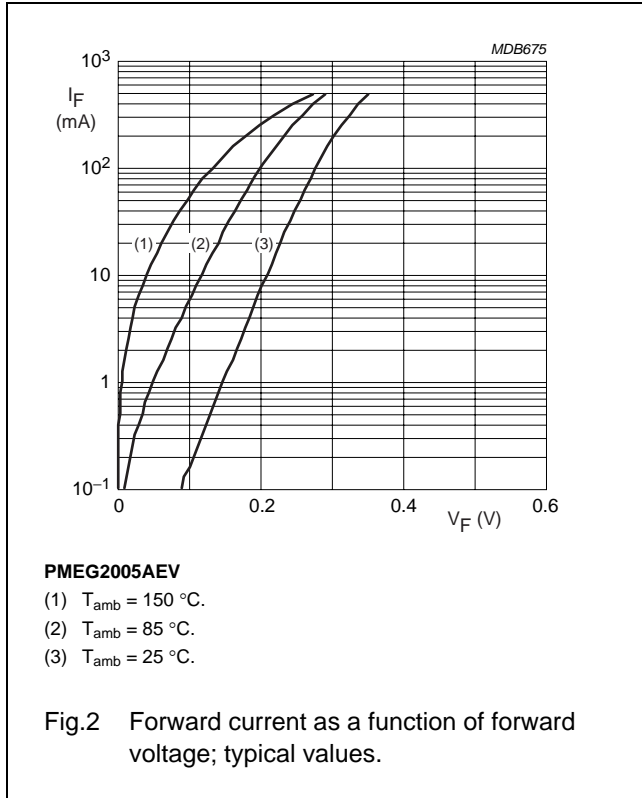
#### Note

1. Pulse test:  $t_p \leq 300\text{ }\mu\text{s}$ ;  $\delta \leq 0.02$ .

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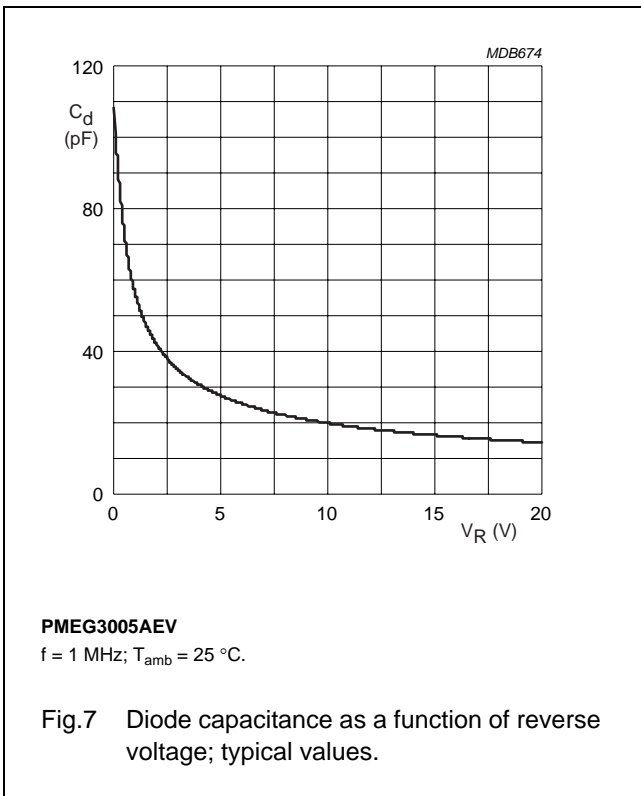
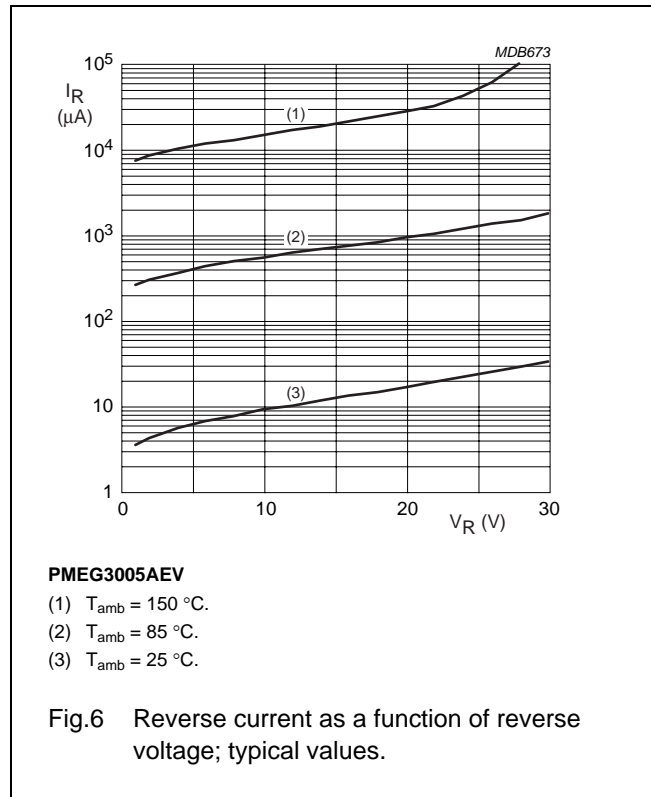
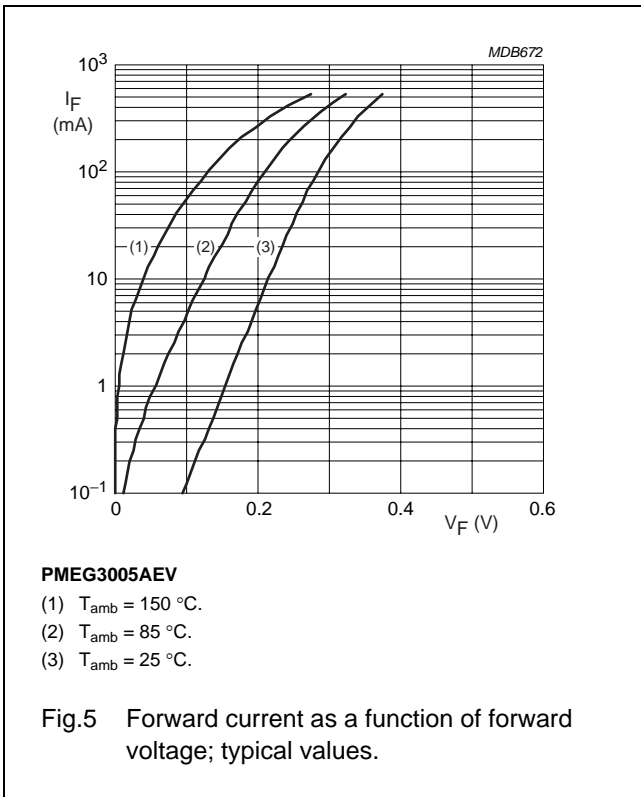
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GRAPHICAL DATA



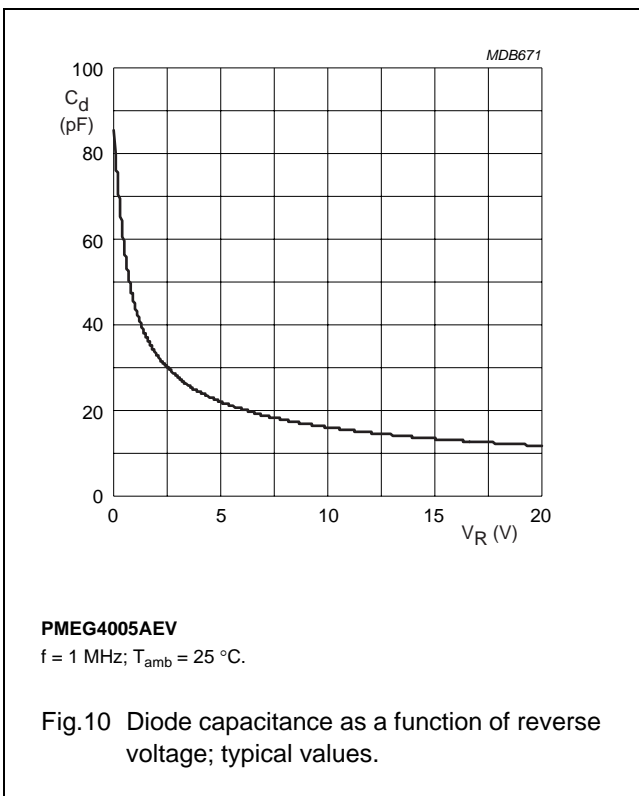
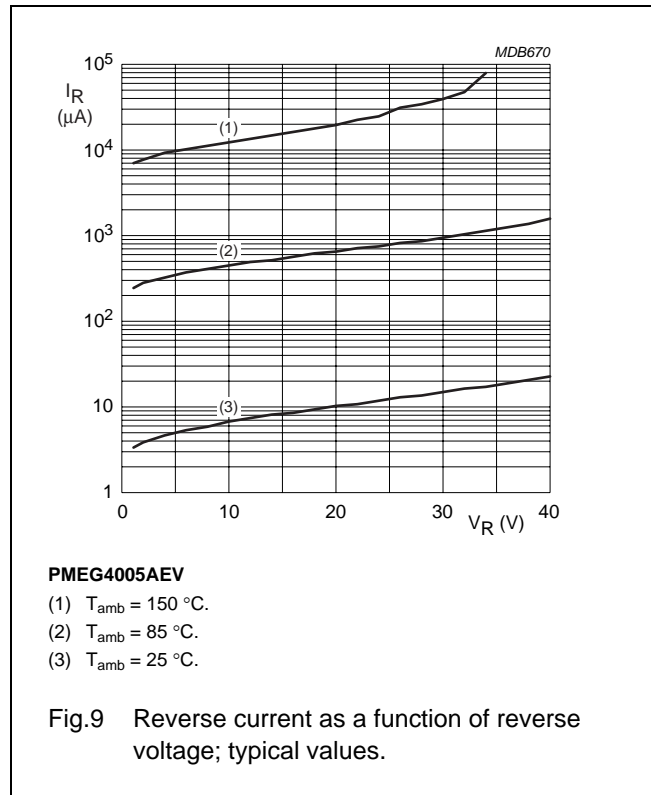
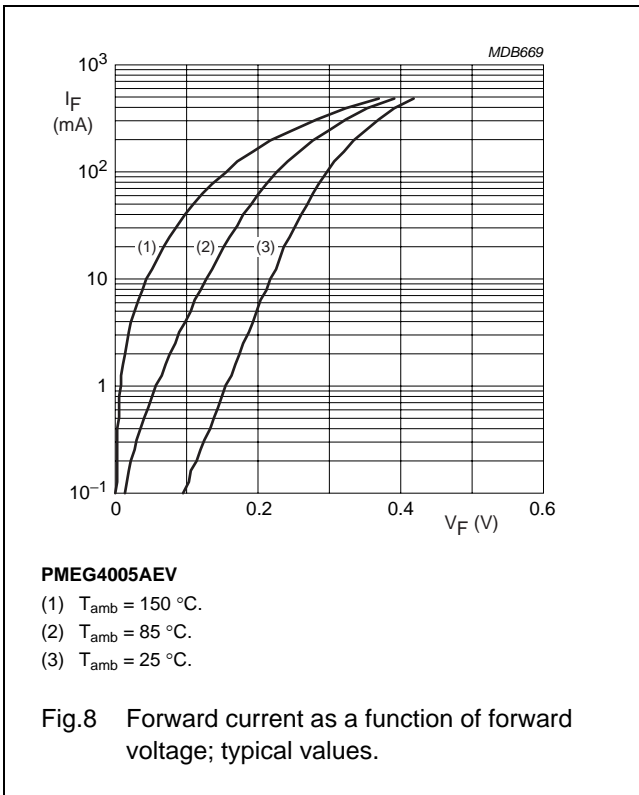
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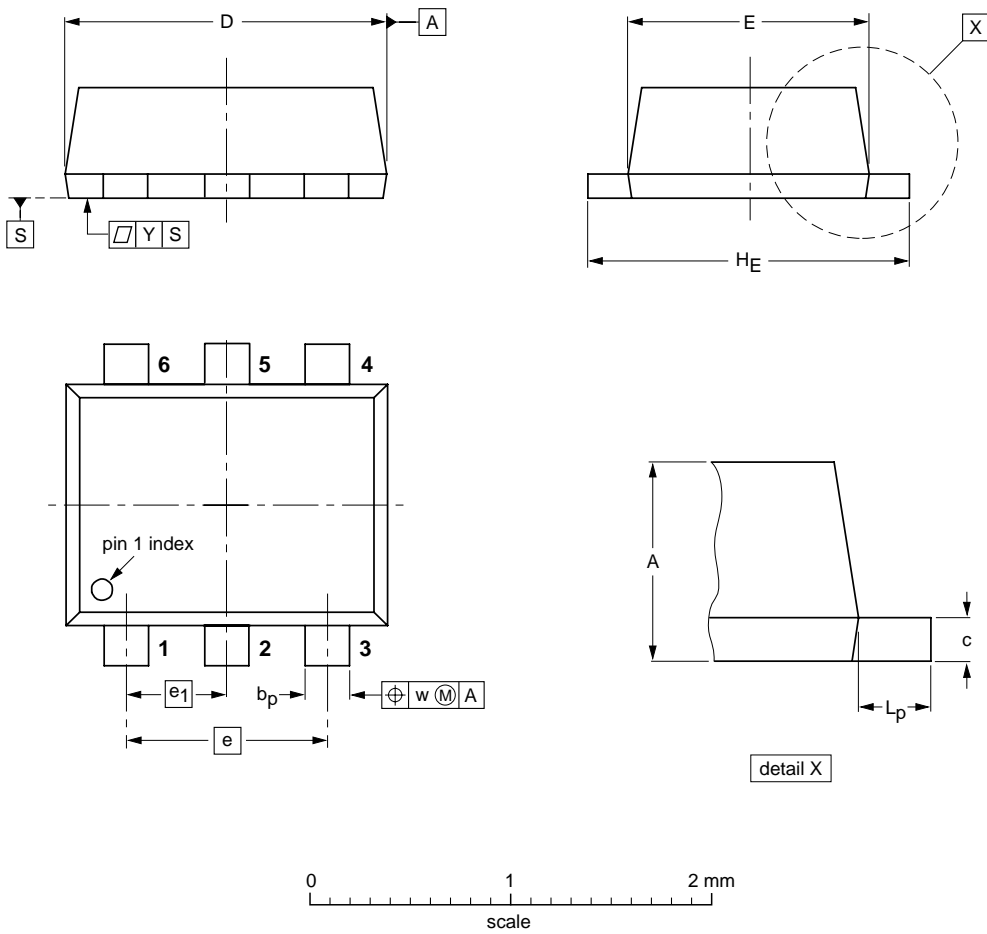
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PACKAGE OUTLINE

Plastic surface mounted package; 6 leads

SOT666



DIMENSIONS (mm are the original dimensions)

UNIT	A	$b_p$	c	D	E	e	$e_1$	$H_E$	$L_p$	w	y
mm	0.6 0.5	0.27 0.17	0.18 0.08	1.7 1.5	1.3 1.1	1.0	0.5	1.7 1.5	0.3 0.1	0.1	0.1

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT666					01-01-04 01-08-27

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**DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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# ***NXP Semiconductors***

## **Customer notification**

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## **Contact information**

For additional information please visit: **<http://www.nxp.com>**

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